- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Supports Unregulated Battery Operation Down to 2.7 V**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**

D, DB, NS, OR PW PACKAGE
(TOP VIEW)

1$\overline{OE}$	1	14	V_{CC}
1A	2	13	4$\overline{OE}$
1Y	3	12	4A
2$\overline{OE}$	4	11	4Y
2A	5	10	3$\overline{OE}$
2Y	6	9	3A
GND	7	8	3Y
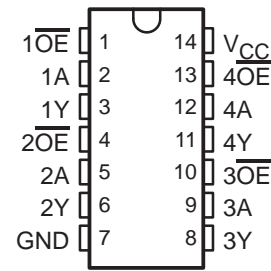
description/ordering information

This bus buffer is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVT125 features independent line drivers with 3-state outputs. Each output is in the high-impedance state when the associated output-enable ($\overline{OE}$) input is high.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SOIC – D	Tube	SN74LVT125D	LVT125
		Tape and reel	SN74LVT125DR	
	SOP – NS	Tape and reel	SN74LVT125NSR	LVT125
	SSOP – DB	Tape and reel	SN74LVT125DBR	LX125
	TSSOP – PW	Tube	SN74LVT125PW	LX125
		Tape and reel	SN74LVT125PWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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TEXAS INSTRUMENTS

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)
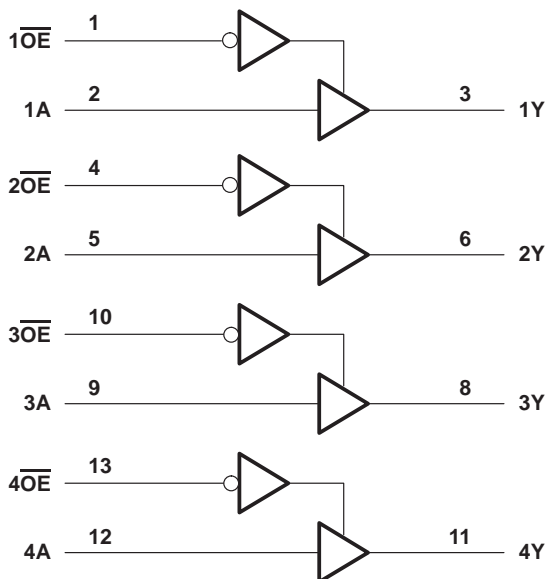
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	−0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1)	−0.5 V to 7 V
Current into any output in the low state, I_O	128 mA
Current into any output in the high state, I_O (see Note 2)	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Output clamp current, I_{OK} ($V_O < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	86°C/W
DB package	96°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

TEXAS INSTRUMENTS

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage		2		V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage			5.5	V
I_{OH}	High-level output current			−32	mA
I_{OL}	Low-level output current			64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	ns/V
T_A	Operating free-air temperature		−40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP[†]	MAX	UNIT
V_{IK}	V_{CC} = 2.7 V,	I_I = −18 mA				−1.2	V
V_{OH}	V_{CC} = MIN to MAX[‡],	I_{OH} = −100 µA		V_{CC}−0.2			V
	V_{CC} = 2.7 V,	I_{OH} = −8 mA		2.4			
	V_{CC} = 3 V	I_{OH} = −32 mA		2			
V_{OL}	V_{CC} = 2.7 V	I_{OL} = 100 µA				0.2	V
		I_{OL} = 24 mA				0.5	
	V_{CC} = 3 V	I_{OL} = 16 mA				0.4	
		I_{OL} = 32 mA				0.5	
		I_{OL} = 64 mA				0.55	
I_I	V_{CC} = 0 or MAX[‡],	V_I = 5.5 V				10	µA
	V_{CC} = 3.6 V	$V_I = V_{CC}$ or GND	Control inputs			±1	
		$V_I = V_{CC}$	Data inputs			1	
		V_I = 0				−5	
I_{off}	V_{CC} = 0,	V_I or V_O = 0 to 4.5 V				±100	µA
$I_{I(hold)}$	V_{CC} = 3 V	V_I = 0.8 V	Data inputs	75			µA
		V_I = 2 V		−75			
I_{OZH}	V_{CC} = 3.6 V,	V_O = 3 V				5	µA
I_{OZL}	V_{CC} = 3.6 V,	V_O = 0.5 V				−5	µA
I_{CC}	V_{CC} = 3.6 V, $V_I = V_{CC}$ or GND	I_O = 0,	Outputs high		0.12	0.19	mA
			Outputs low		4.5	7	
			Outputs disabled		0.12	0.19	
ΔI_{CC}[§]	V_{CC} = 3 V to 3.6 V,	One input at V_{CC} − 0.6 V,	Other inputs at V_{CC} or GND			0.2	mA
C_i	V_I = 3 V or 0					4	pF
C_o	V_O = 3 V or 0					8	pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
[§] This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

TEXAS INSTRUMENTS

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V $\pm$ 0.3 V			V_{CC} = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.7	4		4.5	ns
t_{PHL}			1	2.9	3.9		4.9	
t_{PZH}	$\overline{OE}$	Y	1	3.4	4.7		6	ns
t_{PZL}			1.1	3.4	4.7		6.5	
t_{PHZ}	$\overline{OE}$	Y	1.8	3.7	5.1		5.7	ns
t_{PLZ}			1.3	2.6	4.5		4	

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

PARAMETER MEASUREMENT INFORMATION
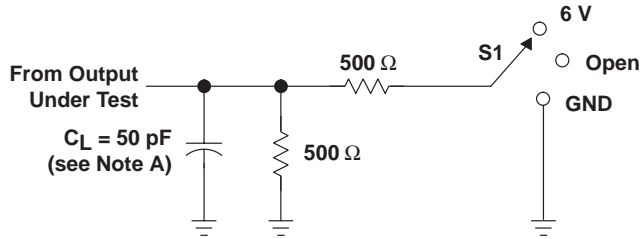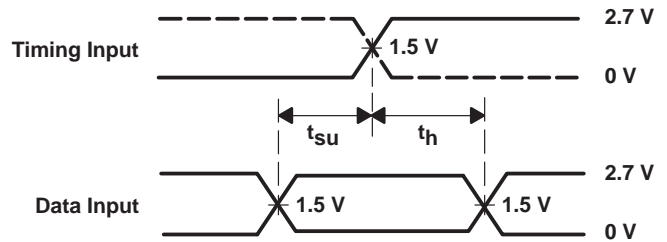
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT FOR OUTPUTS
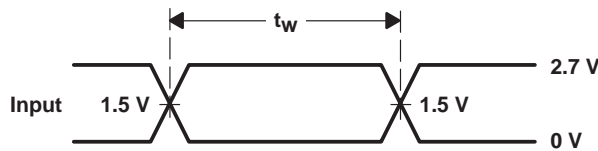
**VOLTAGE WAVEFORMS
PULSE DURATION**

**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**
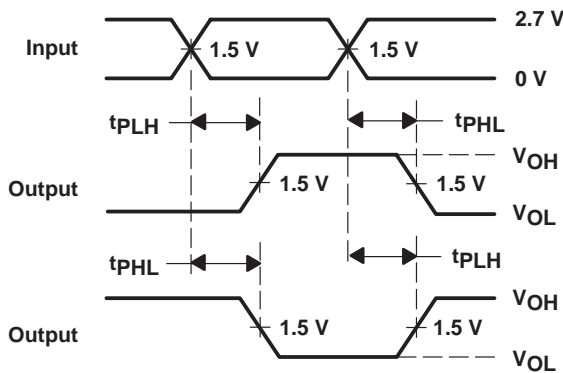
**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**
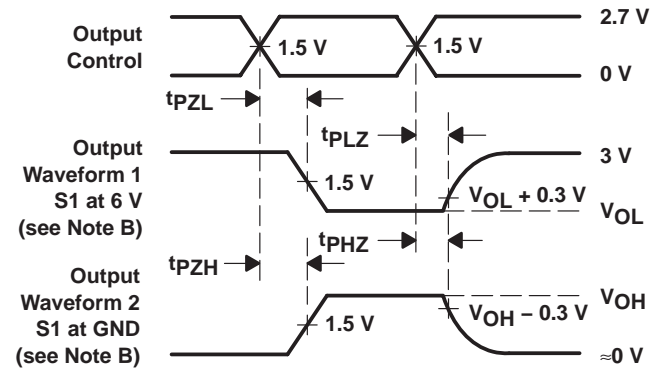
**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

NOTES: A. C_L includes probe and jig capacitance.
   B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
      Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
   D. The outputs are measured one at a time with one transition per measurement.
   E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVT125D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT125	Samples
SN74LVT125DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX125	Samples
SN74LVT125DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT125	Samples
SN74LVT125DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT125	Samples
SN74LVT125NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT125	Samples
SN74LVT125PW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX125	Samples
SN74LVT125PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX125	Samples
SN74LVT125PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LX125	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LVT125 :

● Automotive : SN74LVT125-Q1

● Enhanced Product : SN74LVT125-EP

NOTE: Qualified Version Definitions:

  ● Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

  ● Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT125DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LVT125DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVT125DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVT125NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVT125PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT125DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74LVT125DR	SOIC	D	14	2500	340.5	336.1	32.0
SN74LVT125DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LVT125NSR	SO	NS	14	2000	356.0	356.0	35.0
SN74LVT125PWR	TSSOP	PW	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

TUBE

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LVT125D	D	SOIC	14	50	507	8	3940	4.32
SN74LVT125D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LVT125PW	PW	TSSOP	14	90	530	10.2	3600	3.5

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

DIM	PINS **	14	16	20	24
A MAX		10,50	10,50	12,90	15,30
A MIN		9,90	9,90	12,30	14,70

4040062/C 03/03
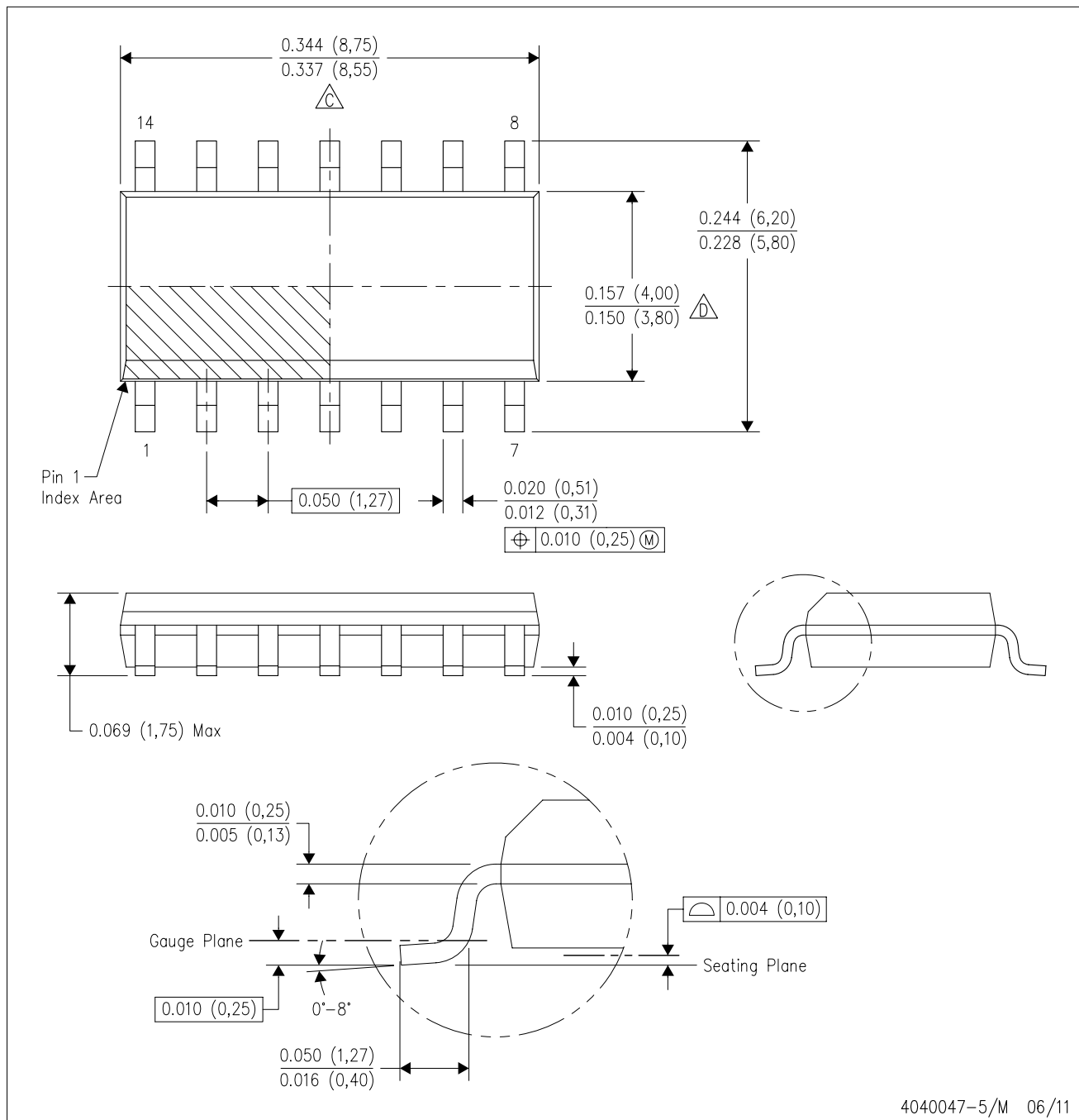
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

4040047−5/M   06/11

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
    ⚠C.   Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
              not exceed 0.006 (0,15) each side.
    ⚠D.   Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
   E.   Reference JEDEC MS−012 variation AB.

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D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

|←—12x1,27

|←—14x0,55

|←—12x1,27

14x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

←—0,60

1,55

Example
Solder Mask Opening
(See Note E)

←—0.07
All Around

4211283−3/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R−PDSO−G14)   PLASTIC SMALL OUTLINE
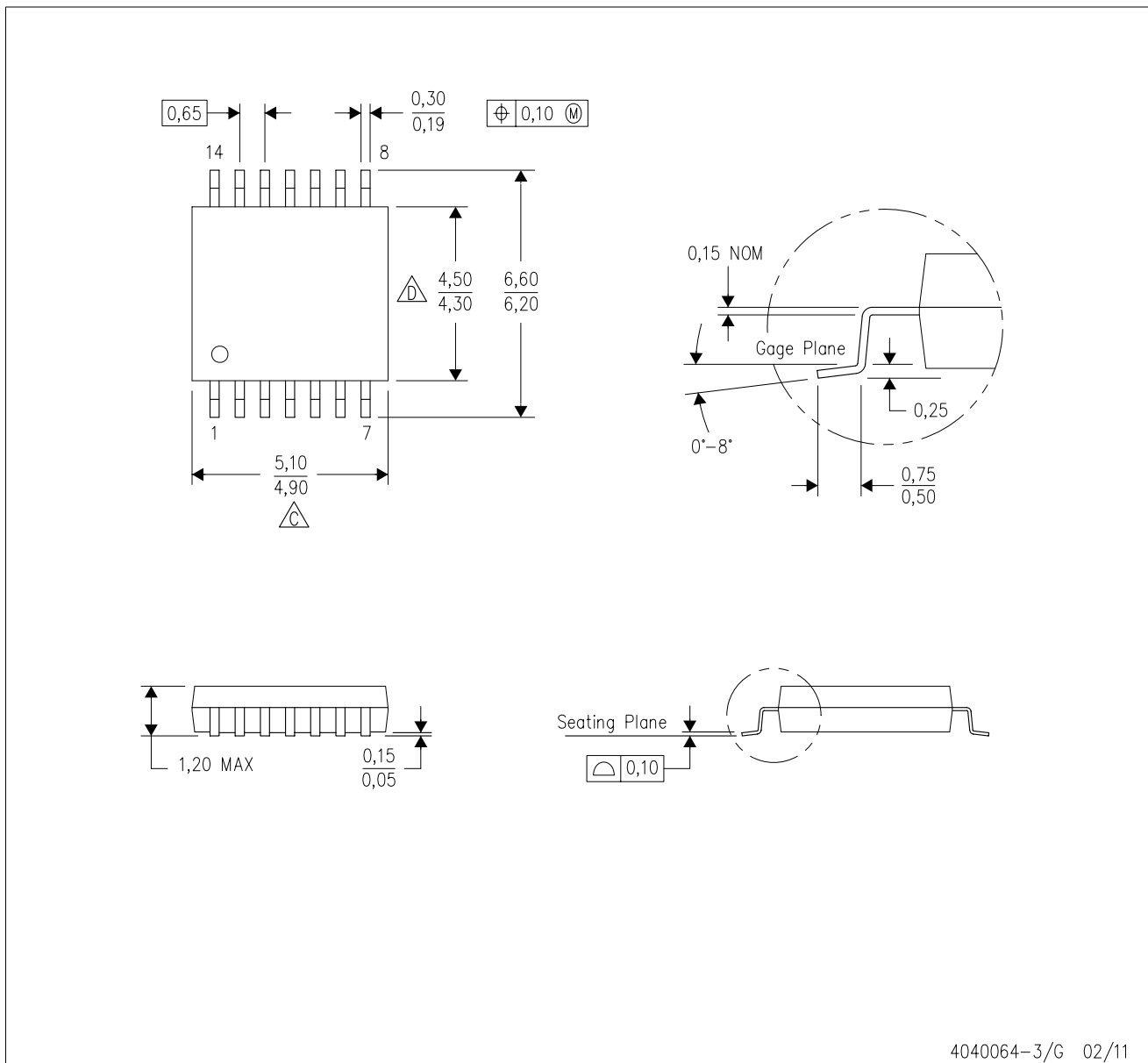
4040064−3/G 02/11

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
         B. This drawing is subject to change without notice.
         C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0,15 each side.
         D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
         E. Falls within JEDEC MO−153

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DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN

0,65

$\frac{0,38}{0,22}$ ⊕ 0,15 Ⓜ

28   15

$\frac{5,60}{5,00}$ $\frac{8,20}{7,40}$

$\frac{0,25}{0,09}$

Gage Plane

0°–8°   0,25

$\frac{0,95}{0,55}$

1   14

A

2,00 MAX   0,05 MIN

Seating Plane

△ 0,10

DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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